



Material Content Data Sheet



Sales Product Name				IKD06N60R		Issued		1. August 2018	
MA#				MA002129238					
Package				PG-TO252-3-342		Weight*		332.93 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.924	0.28	0.28	2775	2775	
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144		
	non noble metal	iron	7439-89-6	0.160	0.05		482		
	non noble metal	copper	7440-50-8	160.096	48.09	48.15	480872	481498	
	non noble metal	aluminium	7429-90-5	0.462	0.14	0.14	1388	1388	
wire	non noble metal	aluminium	7429-90-5	0.462	0.14	0.14	1388	1388	
encapsulation	organic material	carbon black	1333-86-4	1.174	0.35		3525		
	plastics	epoxy resin	-	16.430	4.93		49349		
	inorganic material	silicondioxide	60676-86-0	129.091	38.77	44.05	387745	440619	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11234	11234	
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1572	1572	
solder	non noble metal	tin	7440-31-5	0.022	0.01		65		
	noble metal	silver	7440-22-4	0.027	0.01		81		
	non noble metal	lead	7439-92-1	1.029	0.31	0.33	3091	3237	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17		
	non noble metal	iron	7439-89-6	0.019	0.01		58		
	non noble metal	copper	7440-50-8	19.177	5.76	5.77	57602	57677	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com